FAIRCHILD SEMICONDUCTOR®

2N7274D, 2N7274R 2N7274H

REGISTRATION PENDING
Currently Available as FRM230 (D, R, H)

December 2001

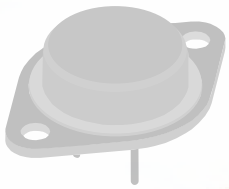
Radiation Hardened N-Channel Power MOSFETs

Features

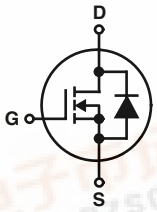
- 8A, 200V, RDS(on) = 0.50Ω
- Second Generation Rad Hard MOSFET Results From New Design Concepts
- Gamma
  - Meets Pre-Rad Specifications to 100KRAD(Si)
  - Defined End Point Specs at 300KRAD(Si) and 1000KRAD(Si)
  - Performance Permits Limited Use to 3000KRAD(Si)
- Gamma Dot
  - Survives 3E9RAD(Si)/sec at 80% BVDSS Typically
  - Survives 2E12 Typically If Current Limited to IDM
- Photo Current - 3.0nA Per-RAD(Si)/sec Typically
- Neutron
  - Pre-RAD Specifications for 1E13 Neutrons/cm^2
  - Usable to 1E14 Neutrons/cm^2
- Single Event - Typically Survives 1E5ions/cm^2 Having an LET ≤ 35MeV/mg/cm^2 and a Range ≥ 30μm at 80% BVDSS

Package

TO-204AA



Symbol



Description

The Harris Semiconductor Sector has designed a series of SECOND GENERATION hardened power MOSFETs of both N and P channel enhancement types with ratings from 100V to 500V, 1A to 60A, and on resistance as low as 25mΩ. Total dose hardness is offered at 100K RAD(Si) and 1000KRAD(Si) with neutron hardness ranging from 1E13n/cm^2 for 500V product to 1E14n/cm^2 for 100V product. Dose rate hardness (GAMMA DOT) exists for rates to 1E9 without current limiting and 2E12 with current limiting. Heavy ion survival from signal event drain burn-out exists for linear energy transfer (LET) of 35 at 80% of rated voltage.

This MOSFET is an enhancement-mode silicon-gate power field effect transistor of the vertical DMOS (VDMOS) structure. It is specially designed and processed to exhibit minimal characteristic changes to total dose (GAMMA) and neutron (n^o) exposures. Design and processing efforts are also directed to enhance survival to heavy ion (SEE) and/or dose rate (GAMMA DOT) exposure.

This part may be supplied as a die or in various packages other than shown above. Reliability screening is available as either non TX (commercial), TX equivalent of MIL-S-19500, TXV equivalent of MIL-S-19500, or space equivalent of MIL-S-19500. Contact the Harris Semiconductor High-Reliability Marketing group for any desired deviations from the data sheet.

Absolute Maximum Ratings (TC = +25°C) Unless Otherwise Specified

		2N7274D, R, H	UNITS
Drain-Source Voltage	VDS	200	V
Drain-Gate Voltage (RGS = 20kΩ)	VDGR	200	V
Continuous Drain Current			
TC = +25°C	ID	8	A
TC = +100°C	ID	5	A
Pulsed Drain Current	IDM	24	A
Gate-Source Voltage	VGS	±20	V
Maximum Power Dissipation			
TC = +25°C	PT	75	W
TC = +100°C	PT	30	W
Derated Above +25°C		0.60	W/°C
Inductive Current, Clamped, L = 100μH, (See Test Figure)	ILM	24	A
Continuous Source Current (Body Diode)	IS	8	A
Pulsed Source Current (Body Diode)	ISM	24	A
Operating And Storage Temperature	TJC, TSTG	-55 to +150	°C
Lead Temperature (During Soldering)			
Distance > 0.063 in. (1.6mm) From Case, 10s Max	TL	300	°C

Specifications 2N7274D, 2N7274R, 2N7274H - Registration Pending

Pre-Radiation Electrical Specifications TC = +25°C, Unless Otherwise Specified

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS MIN	LIMITS MAX	UNITS
Drain-Source Breakdown Volts	BVDSS	VGS = 0, ID = 1mA	200	-	V
Gate-Threshold Volts	VGS(th)	VDS = VGS, ID = 1mA	2.0	4.0	V
Gate-Body Leakage Forward	IGSSF	VGS = +20V	-	100	nA
Gate-Body Leakage Reverse	IGSSR	VGS = -20V	-	100	nA
Zero-Gate Voltage Drain Current	IDSS1 IDSS2 IDSS3	VDS = 200V, VGS = 0 VDS = 160V, VGS = 0 VDS = 160V, VGS = 0, TC = +125°C	- - -	1 0.025 0.25	mA
Rated Avalanche Current	IAR	Time = 20µs	-	24	A
Drain-Source On-State Volts	VDS(on)	VGS = 10V, ID = 8A	-	4.20	V
Drain-Source On Resistance	RDS(on)	VGS = 10V, ID = 5A	-	.50	Ω
Turn-On Delay Time	td(on)	VDD = 100V, ID = 8A	-	30	ns
Rise Time	tr	Pulse Width = 3µs	-	130	
Turn-Off Delay Time	td(off)	Period = 300µs, Rg = 25Ω	-	150	
Fall Time	tf	0 ≤ VGS ≤ 10 (See Test Circuit)	-	80	
Gate-Charge Threshold	QG(th)	VDD = 100V, ID = 8A IGS1 = IGS2 0 ≤ VGS ≤ 20	1	4	nc
Gate-Charge On State	QG(on)		15	60	
Gate-Charge Total	QGM		30	120	
Plateau Voltage	VGP		3	14	V
Gate-Charge Source	QGS		3	14	nc
Gate-Charge Drain	QGD		7	29	
Diode Forward Voltage	VSD	ID = 8A, VGD = 0	0.6	1.8	V
Reverse Recovery Time	TT	I = 8A; di/dt = 100A/µs	-	600	ns
Junction-To-Case	Rθjc		-	1.67	°C/W
Junction-To-Ambient	Rθja	Free Air Operation	-	60	

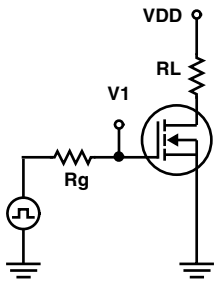


FIGURE 1. SWITCHING TIME TESTING

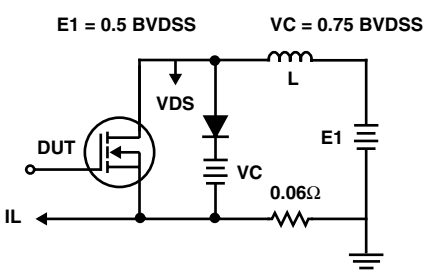


FIGURE 2. CLAMPED INDUCTIVE SWITCHING, ILM

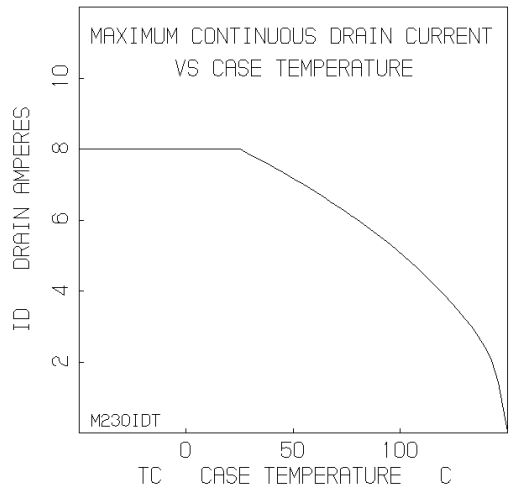
Post-Radiation Electrical Specifications TC = +25°C, Unless Otherwise Specified

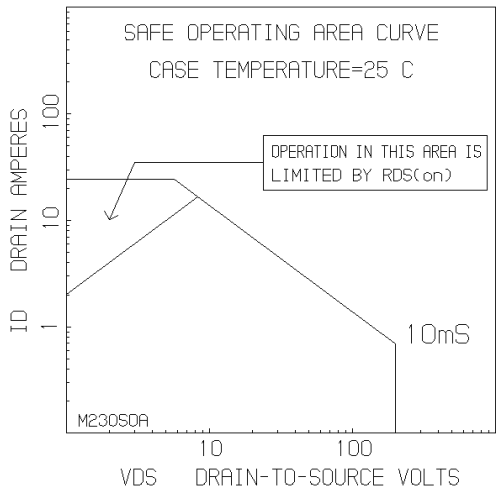
PARAMETER		SYMBOL	TYPE	TEST CONDITIONS	LIMITS		UNITS
					MIN	MAX	
Drain-Source Breakdown Volts	(Note 4, 6)	BVDSS	2N7274D, R	VGS = 0, ID = 1mA	200	-	V
	(Note 5, 6)	BVDSS	2N7274H	VGS = 0, ID = 1mA	190	-	V
Gate-Source Threshold Volts	(Note 4, 6)	VGS(th)	2N7274D, R	VGS = VDS, ID = 1mA	2.0	4.0	V
	(Note 3, 5, 6)	VGS(th)	2N7274H	VGS = VDS, ID = 1mA	1.5	4.5	V
Gate-Body Leakage Forward	(Note 4, 6)	IGSSF	2N7274D, R	VGS = 20V, VDS = 0	-	100	nA
	(Note 5, 6)	IGSSF	2N7274H	VGS = 20V, VDS = 0	-	200	nA
Gate-Body Leakage Reverse	(Note 2, 4, 6)	IGSSR	2N7274D, R	VGS = -20V, VDS = 0	-	100	nA
	(Note 2, 5, 6)	IGSSR	2N7274H	VGS = -20V, VDS = 0	-	200	nA
Zero-Gate Voltage Drain CurrenT	(Note 4, 6)	IDSS	2N7274D, R	VGS = 0, VDS = 160V	-	25	µA
	(Note 5, 6)	IDSS	2N7274H	VGS = 0, VDS = 160V	-	100	µA
Drain-Source On-state Volts	(Note 1, 4, 6)	VDS(on)	2N7274D, R	VGS = 10V, ID = 8A	-	4.20	V
	(Note 1, 5, 6)	VDS(on)	2N7274H	VGS = 16V, ID = 8A	-	6.30	V
Drain-Source On Resistance	(Note 1, 4, 6)	RDS(on)	2N7274D, R	VGS = 10V, ID = 5A	-	0.500	Ω
	(Note 1, 5, 6)	RDS(on)	2N7274H	VGS = 14V, ID = 5A	-	0.750	Ω

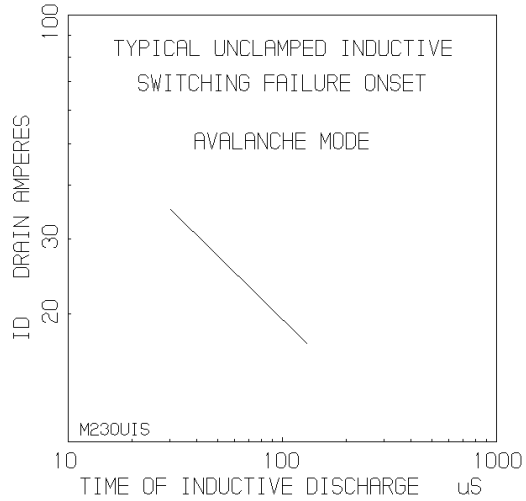
NOTES:

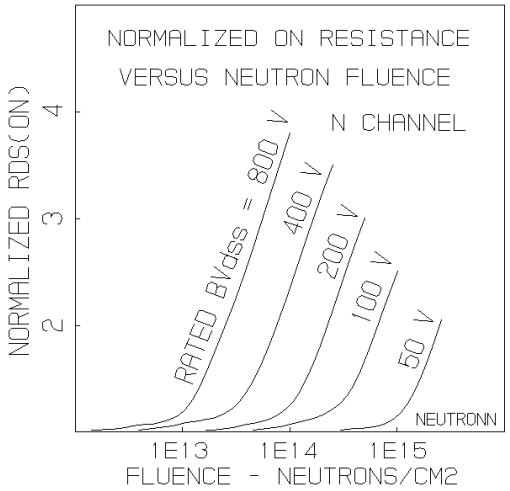
1. Pulse test, 300µs max
2. Absolute value
3. Gamma = 300KRAD(Si)
4. Gamma = 10KRAD(Si) for “D”, 100KRAD(Si) for “R”. Neutron = 1E13
5. Gamma = 1000KRAD(Si). Neutron = 1E13
6. Insitu Gamma bias must be sampled for both VGS = +10V, VDS = 0V and VGS = 0V, VDS = 80% BVDSS
7. Gamma data taken 3/03/90 on TA17632 devices by GE ASTRO SPACE; EMC/SURVIVABILITY LABORATORY; KING OF PRUSSIA, PA 19401
8. Single event drain burnout testing by Titus, J.L., et al of NWSC, Crane, IN at Brookhaven Nat. Lab. Dec 11-14, 1989
9. Neutron derivation, HARRIS Application note AN-8831, Oct. 1988

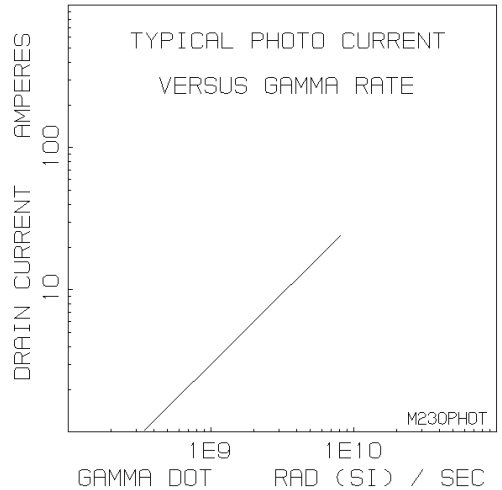
Typical Performance Characteristics

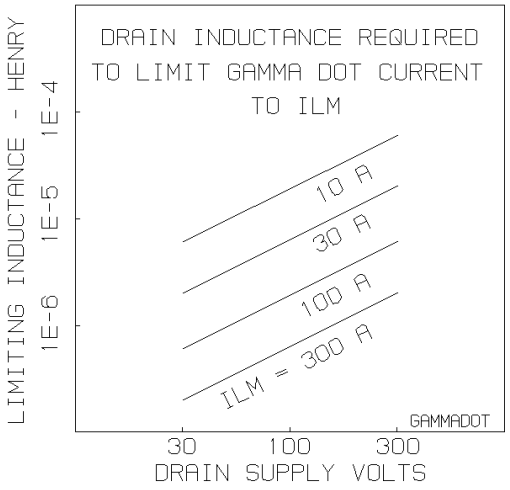




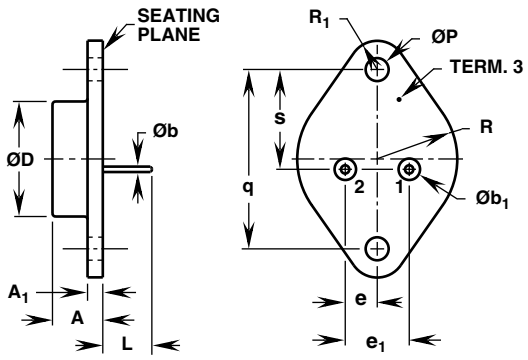








Packaging



NOTES:

1. These dimensions are within allowable dimensions of Rev. C of JEDEC TO-204AA outline dated 11-82.
2. Lead dimension (without solder).
3. Add typically 0.002 inches (0.05mm) for solder coating.
4. Position of lead to be measured 0.250 inches (6.35mm) from bottom of seating plane.
5. Controlling dimension: Inch.
6. Revision 1 dated 1-93.

TO-204AA

JEDEC TO-204AA HERMETIC STEEL PACKAGE

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.310	0.330	7.88	8.38	-
A_1	0.060	0.065	1.53	1.65	-
Øb	0.038	0.042	0.97	1.06	2, 3
$Øb_1$	0.138	0.145	3.51	3.68	-
ØD	-	0.800	-	20.32	-
e	0.215 TYP		5.46 TYP		4
e_1	0.430 BSC		10.92 BSC		4
L	0.440	0.460	11.18	11.68	-
ØP	0.155	0.160	3.94	4.06	-
q	1.187 BSC		30.15 BSC		-
R	0.495	0.525	12.58	13.33	-
R_1	0.131	0.185	3.33	4.69	-
s	0.655	0.675	16.64	17.14	-

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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
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